

规格书编号

SPEC NO :

产品规格书

SPECIFICATION

CUSTOMER 客户: _____

PRODUCT 产品: _____ SAW FILTER _____

MODEL NO 型号: _____ HDF764A F11 _____

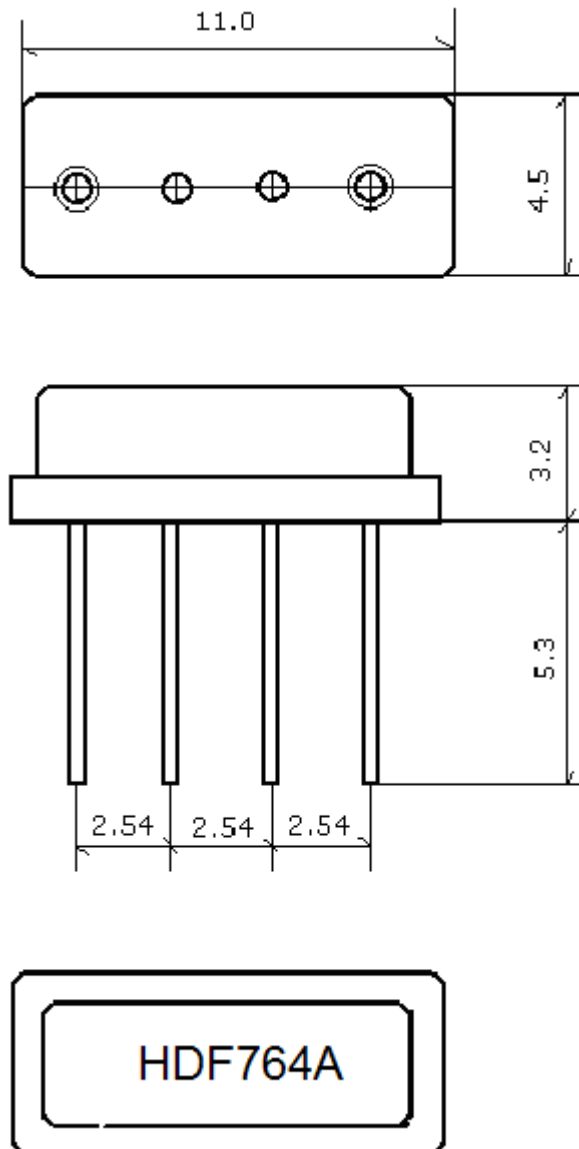
PREPARED 编制: _____ CHECKED 审核: _____

APPROVED 批准: _____ D A T E 日期: _____ 2006-5-11 _____

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司
Shoulder Electronics Limited

1.Package Dimension



2. Marking

HDF764A

- 1.Color: Black or Blue
- 2.764: Center Frequency(MHz)

3.Performance

3.1Application

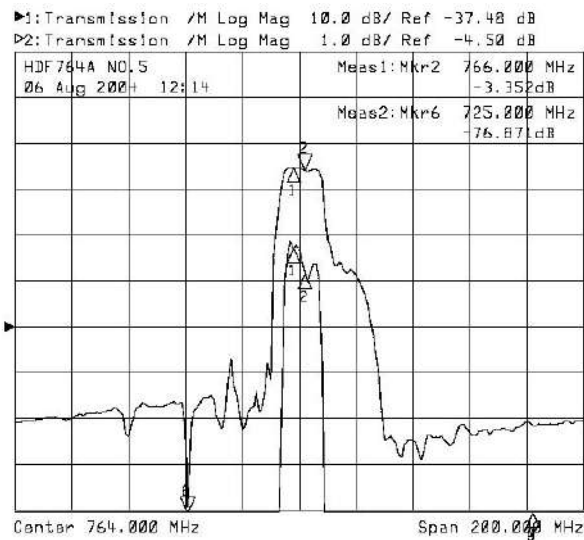
- Low-Loss SAW Filter of cordless system.
- Center Frequency:764.2375 MHz

3.2 Maximum Rating

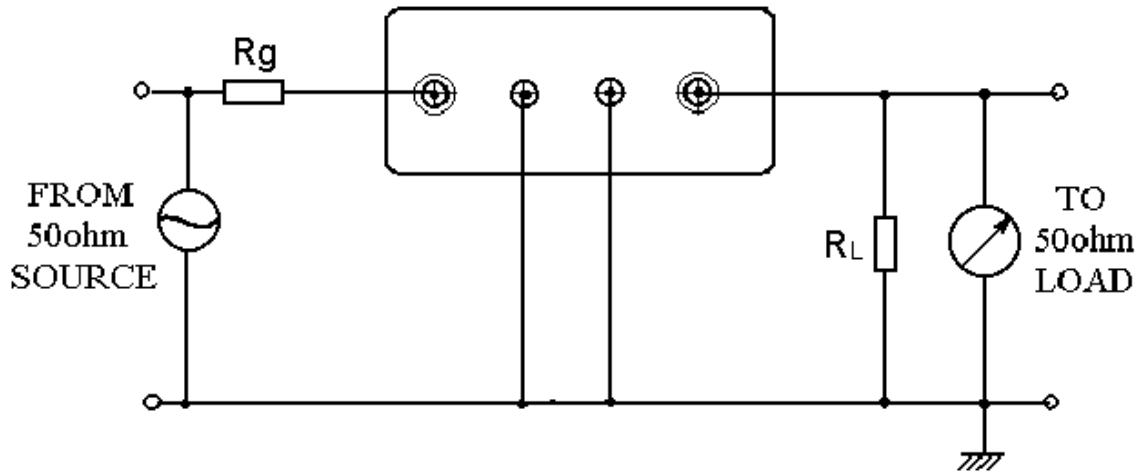
Operation Temperature Range	-40°C to +85°C
Storage Temperature Range	-45°C to +85°C
DC. Permissive Voltage	0 V DC. max.
Maximum Input Power	5dBm

3.3 Electronic Characteristics

Item	Specification(dB)
Center Frequency(fo)	764.2375 MHz
Insertion Loss(dB)	
1.)Fo	5.0max
2.) Δ f-3dB	± 4.0MHz
2.)719-723 MHz	40 min
3.)741-744 MHz	30 min
4.)786-787 MHz	20 min
5.)805-810 MHz	40 min
Ripple deviation (760-768MHz)(dB)	2.0max
Input/output Impedance(Nominal)	50 Ω

3.4 Frequency Characteristics


3.5 Test Circuit



4. ENVIRONMENTAL CHARACTERISTICS

4-1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 3.3.

4-2 Low temperature exposure

Subject the device to -40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 3.3.

4-3 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of +85°C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 3.3.

4-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260°C ±10°C for 10±1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 3.3.

4-5 Solderability

Subject the device terminals into the solder bath at 245°C ±5°C for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 3.3.

4-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. The device shall fulfill the specifications in 3.3.

4-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 3.3.

5. REMARK

5.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

5.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

5.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.